

FEATURES

- Low Supply Current...20 μA Typ
- Single Power Supply
- Rail-to-Rail Common-Mode Input Voltage Range
- Push-Pull Output Circuit
- Low Input-Bias Current

APPLICATIONS

- · Battery Packs for Sensing Battery Voltage
- MP3 Players, Digital Cameras, PMPs
- Cellular Phones, PDAs, Notebook Computers
- Test Equipment
- General-Purpose Low-Voltage Applications

DESCRIPTION/ORDERING INFORMATION

The TLV7256 is a CMOS-type general-purpose dual comparator capable of single power-supply operation and using lower supply currents than the conventional bipolar comparators. Its push-pull output can connect directly to local ICs such as TTL and CMOS circuits.

ORDERING INFORMATION(1)

T _A	PACK	AGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SSOP - DCT	Reel of 3000	TLV7256IDCTR	PREVIEW
-40°C to 85°C		Reel of 250	TLV7256IDCTT	PREVIEW
	VSSOP - DDU	Reel of 3000	TLV7256IDDUR	YAUA

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Typical Application Circuit

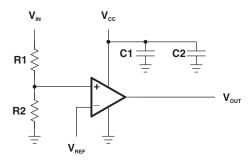
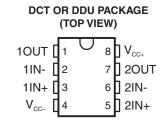


Figure 1. Threshold Detector



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



TLV7256 DUAL COMPARATOR

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Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

				MIN	MAX	UNIT
V _{CC}	Supply voltage			1.5	7	V
V_{ID}	Differential input voltage					V
VI	Input voltage		V _{CC} -	V _{CC+}	V	
Io	Output current				±35	mA
0	Thermal resistance, juction to ambient ⁽²⁾	DCT package			220	°C/W
θ_{JA}	mermai resistance, juction to ambiente	DDU package			227	C/VV
D	Dower discination	DCT package			250	mW
P_D	Power dissipation DDU package				200	IIIVV
T _A	Operating free-air temperature range				85	°C
T _{stg}	Storage temperature range				125	°C

⁽¹⁾ Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended Operating Conditions

		MIN	MAX	UNIT
V_{CC}	Supply voltage	1.8	5	V
T _A	Operating free-air temperature	-40	85	°C

⁽²⁾ Package thermal impedance is calculated according to JESD 51-7.



Electrical Characteristics

 V_{CC+} = 5 V, V_{CC-} = GND, T_A = 25°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	T _A	MIN	TYP	MAX	UNIT	
V	lanut offeet voltege		25°C		±2	±7	mV	
V_{IO}	Input offset voltage		–40°C to 85°C			±8	mv	
I _{IO}	Input offset current		25°C		2		рА	
I _I	Input bias current		25°C		4		pА	
V_{CM}	Common-mode input voltage		25°C	0		V _{CC}	V	
CMDD	Common mode valenties votice	$\Delta V_{CM} = 5 V$	25°C	48	65		dB	
CMRR	Common-mode rejection ratio	0 ≤ V _{CM} ≤ 5 V	–40°C to 85°C	48				
		Output = High, V _{IN} = 5 V	25°C		37	51		
		Output = Low, $V_{IN} = 5 \text{ V}$	25 C		40	60	μΑ	
		Output = High, $V_{IN} = 5 \text{ V}$	-40°C to 85°C			61		
	Cupply ourrent	Output = Low, $V_{IN} = 5 \text{ V}$	-40 C t0 65 C			70		
I _{CC}	Supply current	Output = High, V _{IN} = 2.5 V	25°C		20	32		
		Output = Low, $V_{IN} = 2.5 \text{ V}$	25 C		26	42		
		Output = High, $V_{IN} = 2.5 \text{ V}$	-40°C to 85°C			40		
		Output = Low, $V_{IN} = 2.5 \text{ V}$	-40 C t0 65 C			53		
A_{VD}	Voltage gain	$V_D = 3 \text{ V}, 1 \text{ V} \leq V_{OUT} \leq 4 \text{ V}$	25°C		88		dB	
	Sink current	V 05.V	25°C	25	33		~ ∧	
I _{sink}	Sink current	$V_{OL} = 0.5 \text{ V}$	–40°C to 85°C	20			mA	
	Course current	V 45V	25°C	30	35		~ ∧	
source	Source current	V _{OH} = 4.5 V	-40°C to 85°C	25			mA	
V	Low lovel output voltage	I 5 m A	25°C		0.07	0.12	V	
V_{OL}	Low-level output voltage	$I_{sink} = 5 \text{ mA}$	–40°C to 85°C			0.20	V	
V	High level output voltage	1 - 5 mA	25°C	4.9	4.93		V	
V_{OH}	High-level output voltage	High-level output voltage I _{source} = 5 mA		-40°C to 85°C	4.85			V



Electrical Characteristics

 V_{CC+} = 2.7 V, V_{CC-} = GND, T_A = 25°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	T _A	MIN	TYP	MAX	UNIT	
V	long to offer to yellong		25°C		±2	±8	mV	
V_{IO}	Input offset voltage		-40°C to 85°C			±9	mv	
I _{IO}	Input offset current		25°C		2		рА	
I _I	Input bias current		25°C		4		рА	
V_{CM}	Common-mode input voltage		25°C	0		V _{CC}	V	
CMRR	Common mode rejection ratio	$\Delta V_{CM} = 2.7 \text{ V}$	25°C	42	57		dB	
CIVIKK	Common-mode rejection ratio	0 ≤ V _{CM} ≤ 2.7 V	-40°C to 85°C	42			uБ	
		Output = High, V _{IN} = 2.7 V	25°C		30	55		
		Output = Low, $V_{IN} = 2.7 \text{ V}$	25 C		36	55	μΑ	
		Output = High, $V_{IN} = 2.7 \text{ V}$	-40°C to 85°C			65		
	Cumply ourrent	Output = Low, $V_{IN} = 2.7 \text{ V}$	-40 C to 65 C			65		
I _{CC}	Supply current	Output = High, V _{IN} = 1.35 V	25°C		30	48		
		Output = Low, $V_{IN} = 1.35 \text{ V}$	25 C		35	55		
		Output = High, V _{IN} = 1.35 V	-40°C to 85°C			55		
		Output = Low, $V_{IN} = 1.35 \text{ V}$	-40 C to 65 C			65		
A_{VD}	Voltage gain	$V_D = 1.7 \text{ V}, \ 0.5 \text{ V} \le V_{OUT} \le 2.2 \text{ V}$	25°C		88		dB	
	Sink current	V 05V	25°C	13	18		A	
I _{sink}	Sink current	$V_{OL} = 0.5 \text{ V}$	–40°C to 85°C 1				mA	
	Course current	V 22V	25°C	15	20		A	
Source	Source current	$V_{OH} = 2.2 \text{ V}$	-40°C to 85°C	13			mA	
V	Low lovel output voltage	Land autoritarillana			0.11	0.16	V	
V_{OL}	Low-level output voltage	$I_{sink} = 5 \text{ mA}$	–40°C to 85°C			0.19	V	
V	High level output voltage	el output voltage I _{source} = 5 mA		2.54	2.60		V	
V _{OH}	High-level output voltage			2.45			V	



Electrical Characteristics

 V_{CC+} = 1.8 V, V_{CC-} = GND, T_A = 25°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	T _A	MIN	TYP	MAX	UNIT
.,	lanut offeet voltage		25°C		±2	±8	mV
V _{IO}	Input offset voltage		–40°C to 85°C			±9	mv
I _{IO}	Input offset current		25°C		2		рА
I	Input bias current		25°C		4		pА
V_{CM}	Common-mode input voltage		25°C	0		$V_{CC} - 0.3$	V
CMRR	Common-mode rejection ratio	$\Delta V_{CM} = 5 \text{ V}$	25°C	40	55		dB
CIVIKK	Common-mode rejection ratio	$0 \le V_{CM} \le 5 V$	–40°C to 85°C	40			
		Output = High, V _{IN} = 1.8 V	25°C		30	55	
		Output = Low, $V_{IN} = 1.8 \text{ V}$	25 C		33	47	μΑ
		Output = High, $V_{IN} = 1.8 \text{ V}$	–40°C to 85°C			60	
	Supply current	Output = Low, $V_{IN} = 1.8 \text{ V}$	-40 C to 85 C			51	
I _{CC}	Зарру сапен	Output = High, $V_{IN} = 0.9 \text{ V}$	25°C		20	32	
		Output = Low, $V_{IN} = 0.9 \text{ V}$	25 C		25	37	
		Output = High, $V_{IN} = 0.9 \text{ V}$	–40°C to 85°C			34	
		Output = Low, $V_{IN} = 0.9 \text{ V}$	-40 C to 85 C			40	
A_{VD}	Voltage gain	$V_D = 1.1 \text{ V}, 0.4 \text{ V} \le V_{OUT} \le 1.5 \text{ V}$	25°C		88		dB
	Sink current	V _{OL} = 0.5 V	25°C	6	9		mA
Isink	Sink current	V _{OL} = 0.3 V	–40°C to 85°C	5			ША
	Source current	V _{OH} = 2.2 V	25°C	5	9		mA
Isource	Source current	V _{OH} = 2.2 V	–40°C to 85°C	4			ША
V Low level output voltage		I F			0.2	0.34	V
V _{OL}	Low-level output voltage	I _{sink} = 5 mA	–40°C to 85°C			0.39	V
V	High lovel output voltage		25°C	1.3	1.6		V
V _{OH}	DH High-level output voltage	I _{source} = 5 mA	–40°C to 85°C	1.2			V

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Switching Characteristics

 V_{CC+} = 5 V, V_{CC-} = GND, T_A = 25°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	TYP	UNIT		
	Drangation delay time (turn on)	Overdrive = 100 mV		ns		
t _{PLH}	Propagation delay time (turn on)	TTL step input				
	Dranagation delay time (turn off)	Overdrive = 100 mV	250			
t _{PHL}	Propagation delay time (turn off)	TTL step input	380	ns		
t _{TLH}	Response time	Overdrive = 100 mV	60	no		
t _{THL}	Response time	Overdrive = 100 mv	8	ns		

Switching Characteristics

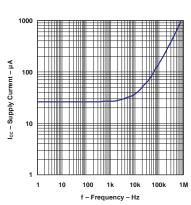
 $V_{CC+} = 3 \text{ V}, V_{CC-} = \text{GND}, T_A = 25^{\circ}\text{C} \text{ (unless otherwise noted)}$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
t _{PLH}	Propagation delay time (turn on)	Overdrive = 100 mV	550	ns
t _{PHL}	Propagation delay time (turn off)	Overdrive = 100 mV	250	ns
t _{TLH}	Decrease time	Outstanding 400 meV	30	
t _{THL}	Response time	Overdrive = 100 mV	8	ns

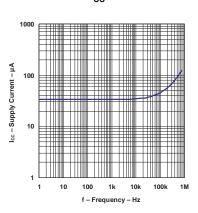


TYPICAL CHARACTERISTICS

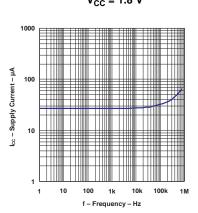
SUPPLY CURRENT
vs
FREQUENCY
V_{CC} = 5 V



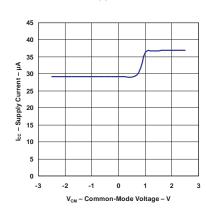
SUPPLY CURRENT
VS
FREQUENCY
V_{CC} = 2.7 V



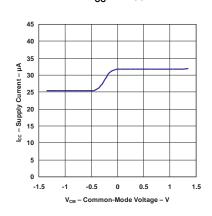
SUPPLY CURRENT
VS
FREQUENCY
V_{CC} = 1.8 V



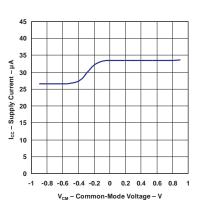
SUPPLY CURRENT vs COMMON-MODE VOLTAGE $V_{CC} = \pm 2.5 \text{ V}$



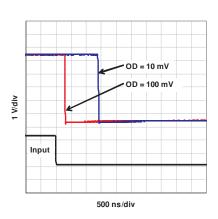
SUPPLY CURRENT VS COMMON-MODE VOLTAGE VCC = ± 1.35 V



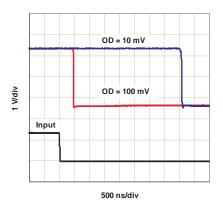
SUPPLY CURRENT vs COMMON-MODE VOLTAGE V_{CC} = ± 0.9 V



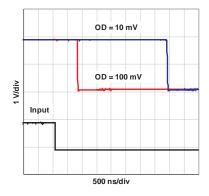
PROPAGATION DELAY TIME, HIGH TO LOW $V_{CC} = 5 \ V$



PROPAGATION DELAY TIME, HIGH TO LOW V_{CC} = 2.7 V



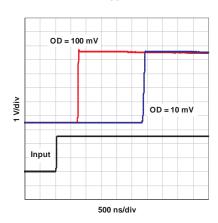
PROPAGATION DELAY TIME, HIGH TO LOW $V_{CC} = 1.8 \text{ V}$



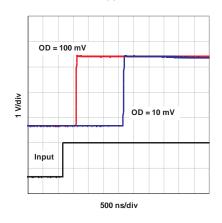


TYPICAL CHARACTERISTICS (continued)

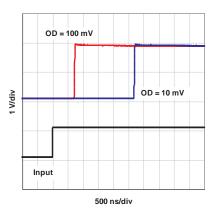
PROPAGATION DELAY TIME, LOW TO HIGH $V_{CC} = 5 \text{ V}$



PROPAGATION DELAY TIME, LOW TO HIGH $V_{CC} = 2.7 \text{ V}$



PROPAGATION DELAY TIME, LOW TO HIGH V_{CC} = 1.8 V





PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
TLV7256IDDUR	ACTIVE	VSSOP	DDU	8	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	YAUA	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

www.ti.com 25-Sep-2019

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV7256IDDUR	VSSOP	DDU	8	3000	180.0	8.4	2.25	3.35	1.05	4.0	8.0	Q3

www.ti.com 25-Sep-2019

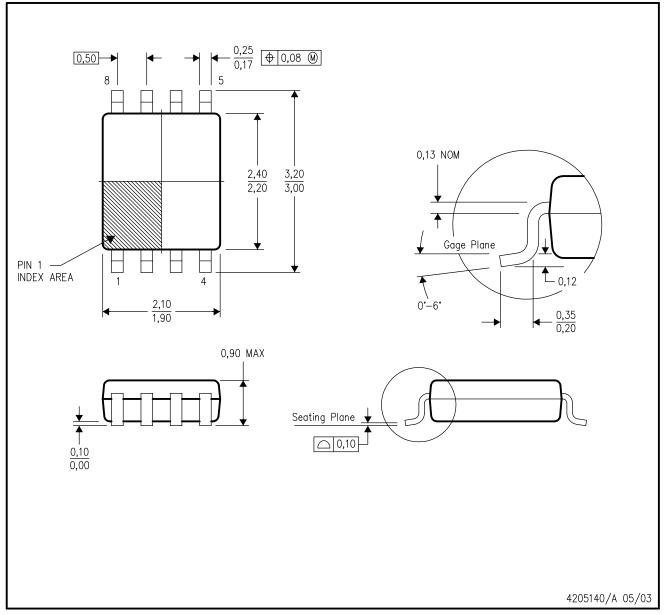


*All dimensions are nominal

I	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
I	TLV7256IDDUR	VSSOP	DDU	8	3000	202.0	201.0	28.0	

DDU (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



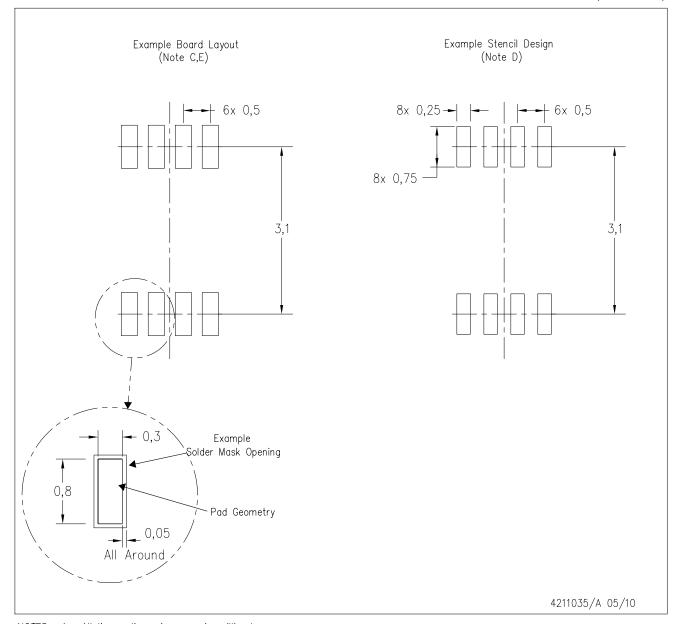
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-187 variation CA.



DDU (S-PDSO-G8)

PLASTIC SMALL OUTLINE PACKAGE (DIE UP)



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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